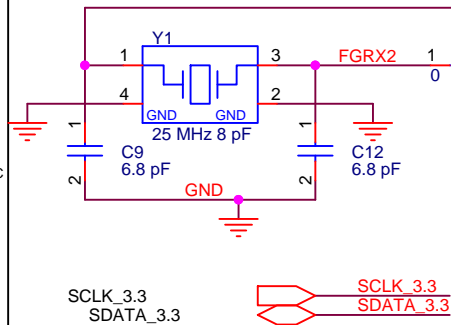
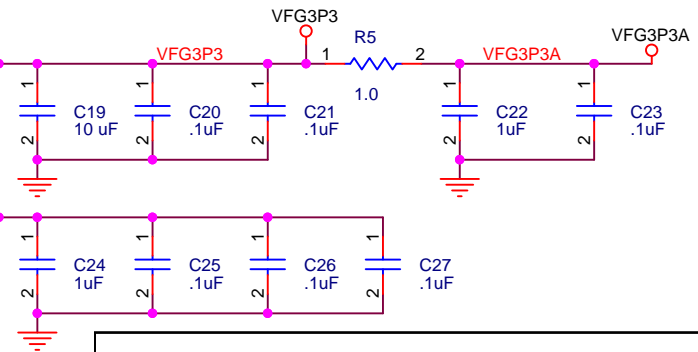
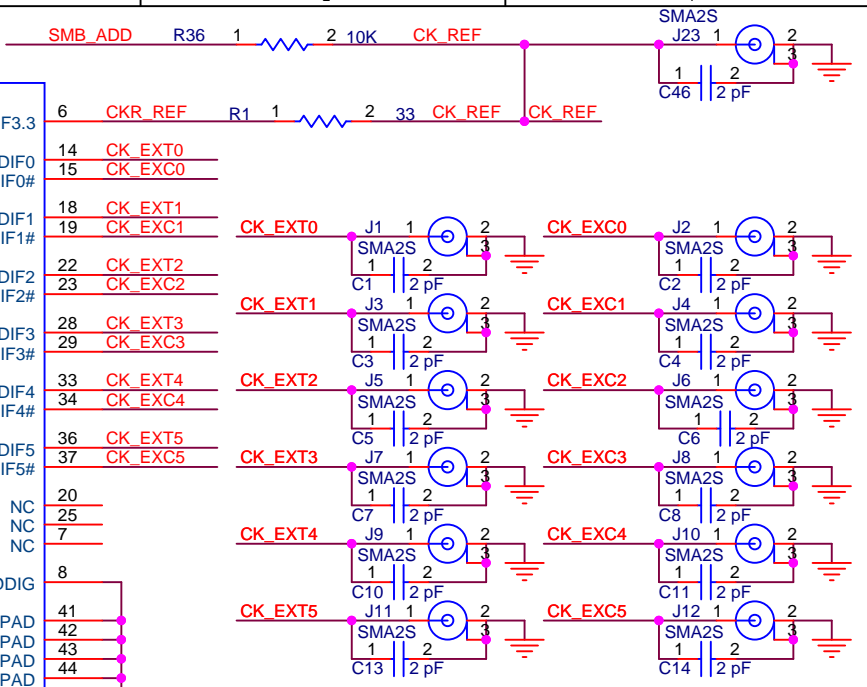
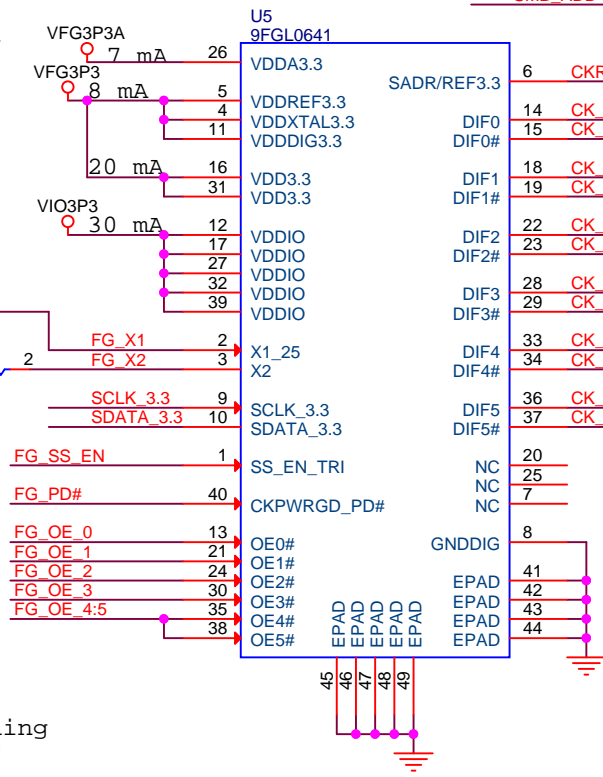
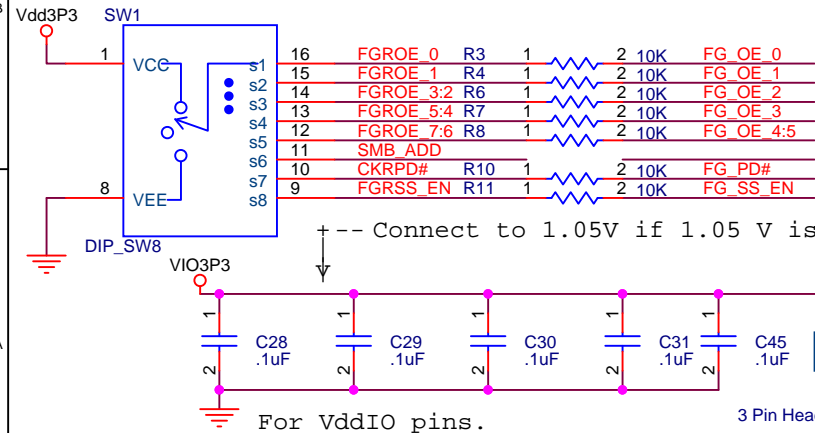


**Layout notes.**

1. Separate Xout and Xin traces by at least 3 x the trace width.
2. Do not share crystal load capacitor ground via with other components.
3. Route power from bead through bulk capacitor pad then through 0.1uF capacitor pad then to clock chip Vdd pad.
4. Do not share ground vias. One ground pin one ground via.
5. Exposed pad should be grounded but is not required.

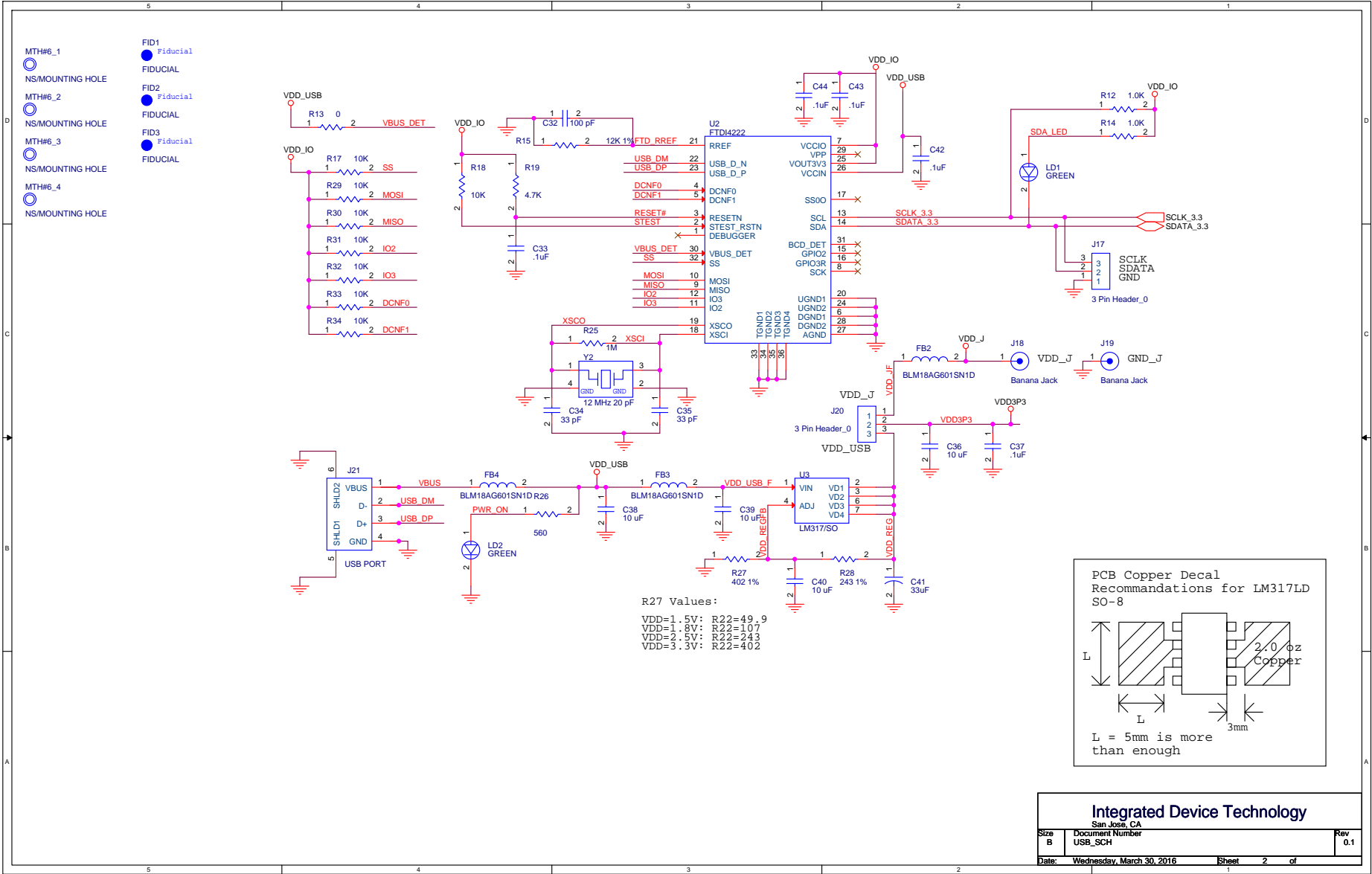


s5:0 1 = Stop low/low, 0 = Running  
 s6: 1 = Add 0xD4, 0 = Add 0xD0  
 s7: 1 = Enable, 0 = Pwr Dwn  
 s8: 1 = -0.5% Spread, MID = -.25%, 0 = No Spread



**Integrated Device Technology**  
 San Jose, CA

Size A	Document Number 9FGL0641_EVB	Rev B
Date: Wednesday, March 30, 2016		Sheet 1 of 2



- MTH#6\_1 NS/MOUNTING HOLE
- MTH#6\_2 NS/MOUNTING HOLE
- MTH#6\_3 NS/MOUNTING HOLE
- MTH#6\_4 NS/MOUNTING HOLE

- FID1 FIDUCIAL
- FID2 FIDUCIAL
- FID3 FIDUCIAL

R27 Values:  
 VDD=1.5V: R22=49.9  
 VDD=1.8V: R22=107  
 VDD=2.5V: R22=243  
 VDD=3.3V: R22=402

